

EAST Search History**EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S104	34	S102 and "29"/\$.ccls.	USPAT	OR	ON	2010/09/13 01:09
S103	9	S102 and "360"/\$.ccls.	USPAT	OR	ON	2010/09/13 01:09
S102	623	(heat\$3 thermal\$4) near1 (coil layer film element unit sink) with (position\$3 align\$4 identif\$6 data information) near2 (mark pattern tag label number)	USPAT	OR	ON	2010/09/13 01:08
S101	55	360/235.3.ccls.	US-PGPUB; USPAT	OR	ON	2010/09/10 10:00
S100	127	360/235.1.ccls.	US-PGPUB; USPAT	OR	ON	2010/09/10 10:00
S99	80	360/125.39.ccls.	US-PGPUB; USPAT	OR	ON	2010/09/10 10:00
S98	47	360/125.38.ccls.	US-PGPUB; USPAT	OR	ON	2010/09/10 10:00
S97	57	360/125.41.ccls.	US-PGPUB; USPAT	OR	ON	2010/09/10 10:00
S96	20	360/123.45.ccls.	US-PGPUB; USPAT	OR	ON	2010/09/10 10:00
S95	23	360/123.24.ccls.	US-PGPUB; USPAT	OR	ON	2010/09/10 10:00
S94	19	S93 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/09/10 09:59
S93	2326	(seed buffer intermediate under) near1 (layer film membrane) with (substrate wafer ceramic base semiconductor) with (touch\$3 contact\$3) with (pattern\$4 hole opening)	US-PGPUB; USPAT	OR	ON	2010/09/10 09:59

S92	25	("20020081778" "20020154451" "20030039067" "20030048578" "20030067716" "20030067717" "20040070870" "20040223257" "20050024957" "20050068671" "20050094319" "4405961" "5278713" "5793578" "5935644" "6105381" "6181514" "6381094" "6396660" "6455174" "6700752" "6760191" "6859343" "6909674").PN. OR ("7170713").URPN.	US-PGPUB; USPAT; USOOR	OR	ON	2010/09/10 09:36
S91	1	(10/215230).APP.	USPAT; USOOR	OR	ON	2010/09/10 09:36
S90	13	S89 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/09/10 09:28
S89	351	(heat\$3 thermal\$4) near1 (coil layer film element unit) with (under below intermediate middle center between) with (substrate alumina carbide base) with (MR sensor read\$3 shield)	USPAT	OR	ON	2010/09/10 09:27
S88	6	("2004/0027719").URPN.	USPAT	OR	ON	2010/09/10 09:18
S87	1	"20040027719".pn.	US-PGPUB; USPAT	OR	ON	2010/09/10 09:10
S74	35	S73 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/08/30 12:41
S73	2345	(seed buffer intermediate under) near1 (layer film membrane) with (substrate wafer ceramic base semiconductor) with (between center middle interpos\$3) with (pattern \$4 hole opening)	US-PGPUB; USPAT	OR	ON	2010/08/30 12:41
S72	6	S71 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/08/30 12:41

S71	459	(seed buffer intermediate under) near1 (layer film membrane) with (substrate wafer ceramic base semiconductor) with (between center middle interpos\$3) with (pattern \$4 hole opening) with (charge or static or ESD or electric or surge or shock or electrostatic or discharge or radiation or noise or conductive)	US-PGPUB; USPAT	OR	ON	2010/08/30 12:41
S70	19	S69 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/08/30 12:41
S69	2316	(seed buffer intermediate under) near1 (layer film membrane) with (substrate wafer ceramic base semiconductor) with (touch\$3 contact\$3) with (pattern\$4 hole opening)	US-PGPUB; USPAT	OR	ON	2010/08/30 12:41
S68	55	360/235.3.ccls.	US-PGPUB; USPAT	OR	ON	2010/08/30 12:18
S67	127	360/235.1.ccls.	US-PGPUB; USPAT	OR	ON	2010/08/30 12:18
S66	80	360/125.39.ccls.	US-PGPUB; USPAT	OR	ON	2010/08/30 12:18
S65	47	360/125.38.ccls.	US-PGPUB; USPAT	OR	ON	2010/08/30 12:18
S64	57	360/125.41.ccls.	US-PGPUB; USPAT	OR	ON	2010/08/30 12:18
S63	20	360/123.45.ccls.	US-PGPUB; USPAT	OR	ON	2010/08/30 12:18
S62	23	360/123.24.ccls.	US-PGPUB; USPAT	OR	ON	2010/08/30 12:14

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S86	0	S83 and 360/235.1.ccls.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:41
S85	0	S83 and 360/235.3.ccls.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:41

S84	0	S83 and 360/125.38. ccls.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:41
S83	3051	((seed buffer intermediate under) near1 (layer film membrane) with (substrate wafer ceramic base semiconductor) with (pattern\$4 hole opening)).clm.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:41
S82	0	S76 and 360/125.38. ccls.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:38
S81	0	S75 and 360/125.38. ccls.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:38
S80	0	S75 and 360/235.1.ccls.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:36
S79	0	S76 and 360/235.1.ccls.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:36
S78	0	S76 and 360/235.3.ccls.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:36
S77	0	S75 and 360/235.3.ccls.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:36
S76	665	((seed buffer intermediate under) near1 (layer film membrane) with (substrate wafer ceramic base semiconductor) with (between center middle interpos\$3) with (pattern\$4 hole opening)).clm.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:36
S75	5732	((between middle center intermediate) with (film layer membrane) with (position\$3 align\$4 identif\$6 data information) with (mark pattern tag label number)).clm.	US-PGPUB; USPAT; UPAD	OR	ON	2010/08/30 12:35

9/13/2010 5:02:26 PM

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